

6th Generation CoolSiC™

650V SiC Schottky Diode

The CoolSiC™ Generation 6 is the leading edge technology from Infineon for the SiC Schottky Barrier diodes. The Infineon proprietary diffusion soldering process is combined with a more compact design, thin-wafer technology and a novel Schottky metal system. The result is a family of products with improved efficiency over all load conditions, resulting from a lower figure of merit ($Q_c \times V_F$). CoolSiC™ Generation 6 has been designed to complement our 600V and 650V CoolMOS™ 7 families, meeting the most stringent application requirements in this voltage range.

Table 1 Key performance parameters

Parameter	Value	Unit
V_{RRM}	650	V
$Q_C (V_R = 400 \text{ V})$	12.2	nC
$E_C (V_R = 400 \text{ V})$	2.2	μJ
$I_F (T_C \leq 145 \text{ °C}, D = 1)$	8	A
$V_F (I_F = 8 \text{ A}, T_j = 25 \text{ °C})$	1.25	V

Table 2 Package information

Type / ordering Code	Package	Marking
IDH08G65C6	PG-TO220-2	D0865C6



Features

- Best in class forward voltage (1.25 V)
- Best in class figure of merit ($Q_c \times V_F$)
- High dv/dt ruggedness (150 V/ns)

Benefits

- System efficiency improvement
- System cost and size savings due to the reduced cooling requirements
- Enabling higher frequency and increased power density

Potential Applications

- Power factor correction in SMPS
- Solar inverter
- Uninterruptible power supply

Product Validation

- Qualified for industrial applications according to the relevant tests of JEDEC (J-STD20 and JESD22)



Table of Content

1	Maximum ratings	3
2	Thermal characteristics	3
3	Electrical characteristics	4
3.1	Static characteristics	4
3.2	AC characteristics	4
4	Diagrams	5
5	Simplified forward characteristic	7
6	Package outlines	8

1 Maximum ratings

Table 3 Maximum ratings

Parameter	Symbol	Values			Unit	Note/Test condition
		Min.	Typ.	Max.		
Continuous forward current	I_F	-	-	8	A	$T_C \leq 145\text{ °C}, D = 1$
		-	-	11		$T_C \leq 125\text{ °C}, D = 1$
		-	-	20		$T_C \leq 25\text{ °C}, D = 1$
Surge-repetitive forward current, sine halfwave ¹	$I_{F,RM}$	-	-	35		$T_C = 25\text{ °C}, t_p = 10\text{ ms}$
Surge non-repetitive forward current, sine halfwave	$I_{F,SM}$	-	-	47		$T_C = 25\text{ °C}, t_p = 10\text{ ms}$
		-	-	37		$T_C = 150\text{ °C}, t_p = 10\text{ ms}$
Non-repetitive peak forward current	$I_{F,max}$	-	-	530	$T_C = 25\text{ °C}, t_p = 10\text{ }\mu\text{s}$	
i^2t value	$\int i^2 dt$	-	-	11	A ² s	$T_C = 25\text{ °C}, t_p = 10\text{ ms}$
		-	-	6.9		$T_C = 150\text{ °C}, t_p = 10\text{ ms}$
Repetitive peak reverse voltage	V_{RRM}	-	-	650	V	$T_C = 25\text{ °C}$
Diode dv/dt ruggedness	dv/dt	-	-	150	V/ns	$V_R = 0..480\text{ V}$
Power dissipation	P_{tot}	-	-	63	W	$T_C = 25\text{ °C}, R_{thJC,max}$
Operating and storage temperature	T_j	-55	-	175	°C	-
	T_{stg}					
Mounting torque	-	-	-	70	Ncm	M3 screw

2 Thermal characteristics

Table 4 Thermal characteristics (PG-TO-220-2)

Parameter	Symbol	Values			Unit	Note/Test condition
		Min.	Typ.	Max.		
Thermal resistance, junction-case	R_{thJC}	-	1.4	2.4	K/W	-
Thermal resistance, junction-ambient	R_{thJA}	-	-	62		leaded
Soldering temperature, wavesoldering only allowed at leads	T_{sold}	-	-	260	°C	1.6 mm (0.063 in.) from case for 10 s

¹ The surge-repetitive forward current test was performed with 1000 pulses (half-wave rectified sine with the 10 ms period).

3 Electrical characteristics

3.1 Static characteristics

Table 5 Static characteristics

Parameter	Symbol	Values			Unit	Note/Test condition
		Min.	Typ.	Max.		
DC blocking voltage	V_{DC}	650	–	–	V	$T_j = 25\text{ °C}$
Diode forward voltage	V_F	–	1.25	1.35		$I_F = 8\text{ A}, T_j = 25\text{ °C}$
		–	1.5	–		$I_F = 8\text{ A}, T_j = 150\text{ °C}$
Reverse current	I_R	–	0.8	27	μA	$V_R = 420\text{ V}, T_j = 25\text{ °C}$
		–	27	–		$V_R = 420\text{ V}, T_j = 125\text{ °C}$
		–	62	–		$V_R = 420\text{ V}, T_j = 150\text{ °C}$

3.2 AC characteristics

Table 6 AC characteristics

Parameter	Symbol	Values			Unit	Note/Test Condition
		Min.	Typ.	Max.		
Total capacitive charge	Q_C	–	12.2	–	nC	$V_R = 400\text{ V}, T_j = 150\text{ °C},$ $di/dt = 200\text{ A}/\mu\text{s}, I_F \leq I_{F,MAX}$
Total capacitance	C	–	401	–	pF	$V_R = 1\text{ V}, f = 1\text{ MHz},$ $T_j = 25\text{ °C}$
		–	24	–		$V_R = 300\text{ V}, f = 1\text{ MHz},$ $T_j = 25\text{ °C}$
		–	23	–		$V_R = 600\text{ V}, f = 1\text{ MHz},$ $T_j = 25\text{ °C}$

4 Diagrams

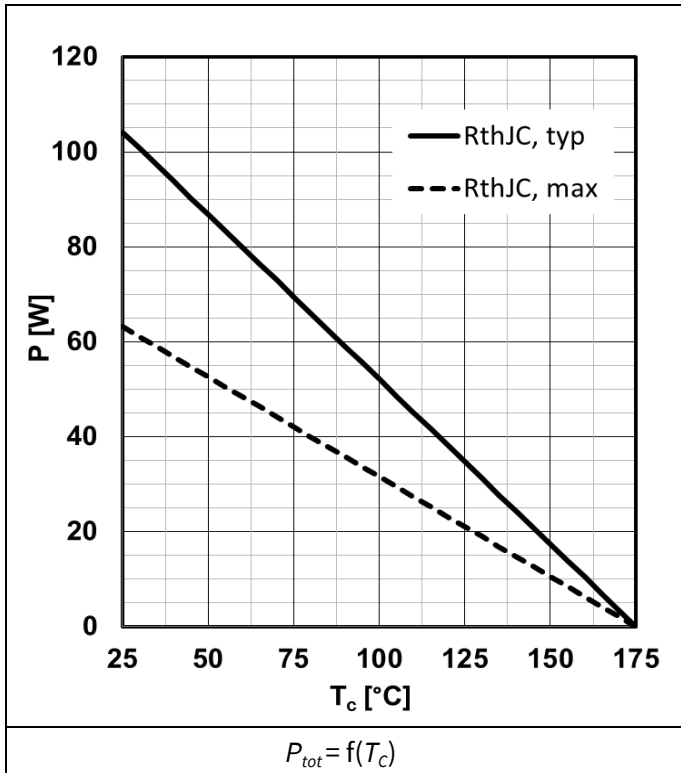


Figure 1 Power dissipation

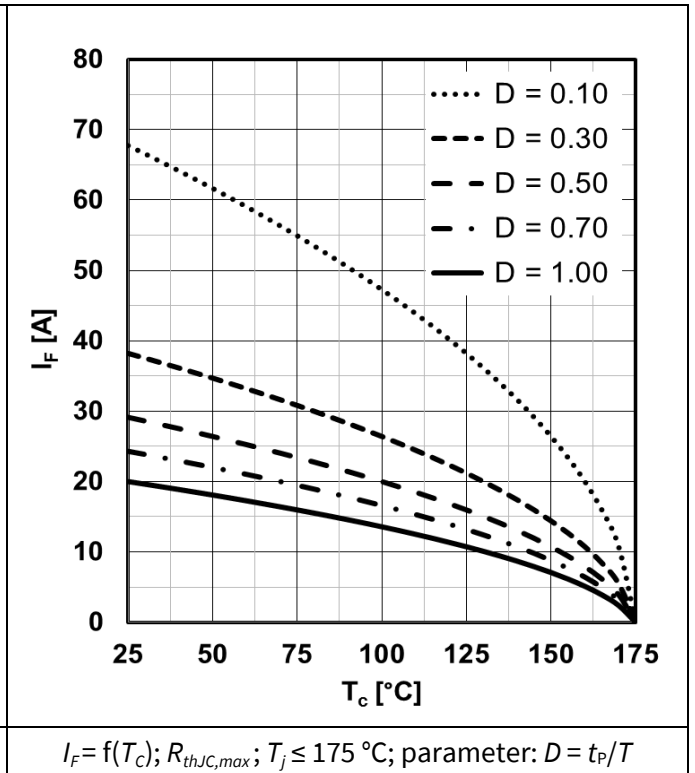


Figure 2 Max. forward current

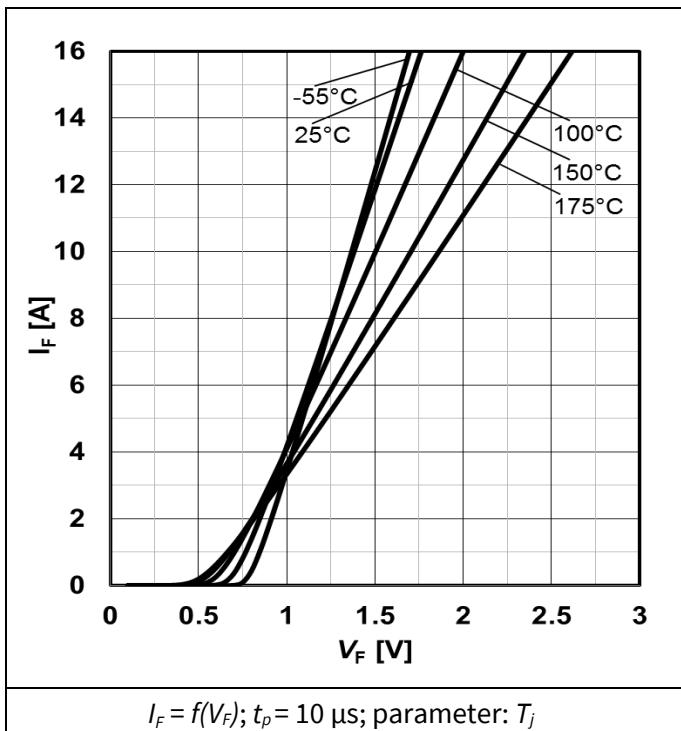


Figure 3 Typ. forward characteristics

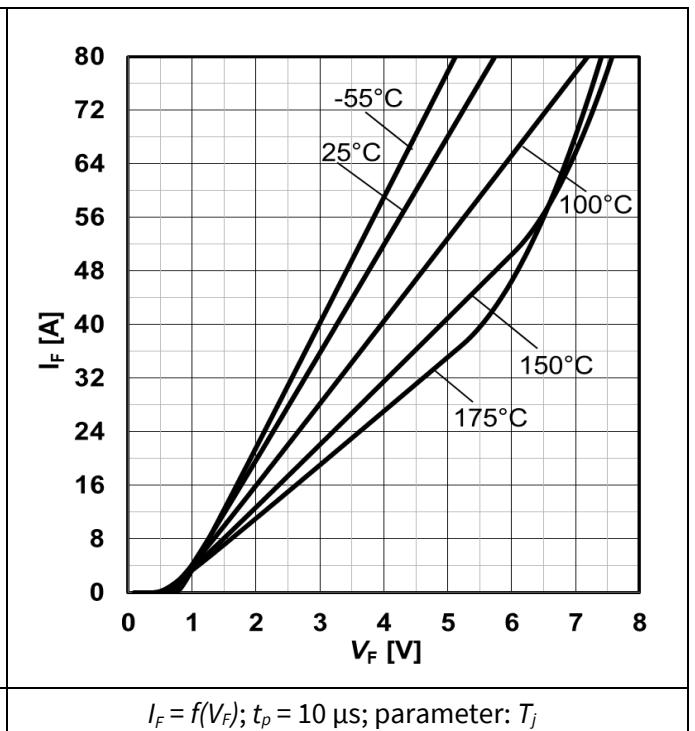


Figure 4 Typ. forward characteristics in surge current

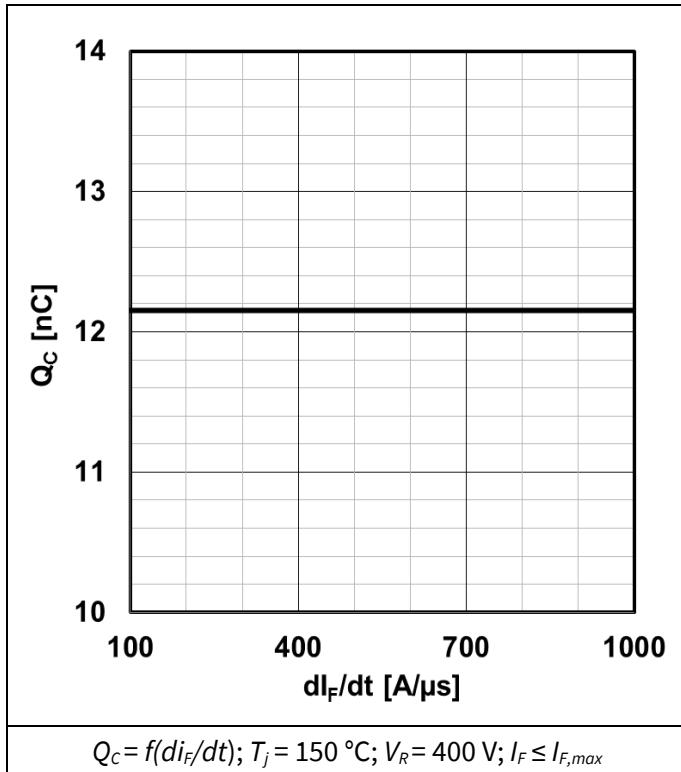


Figure 5 Typ. cap. charge vs. current slope

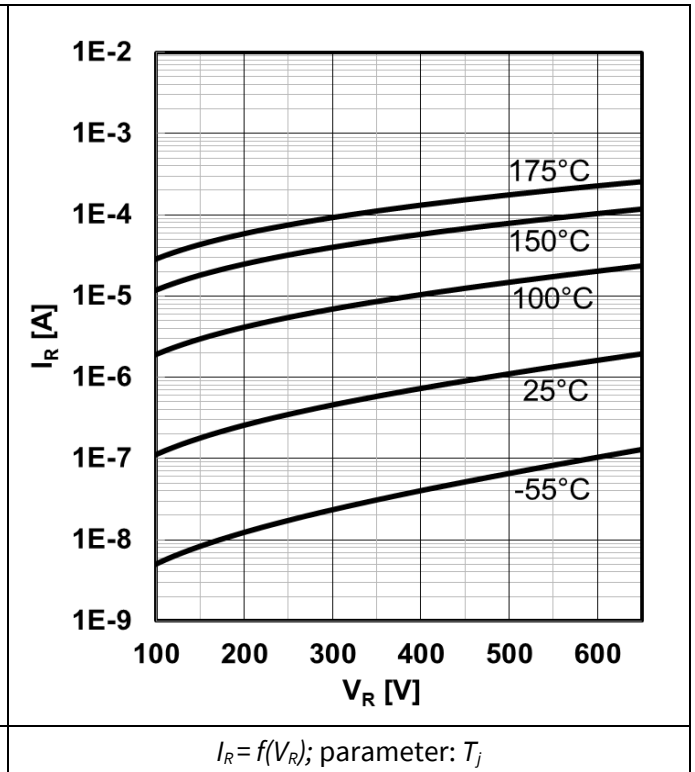


Figure 6 Typ. reverse current vs. reverse voltage

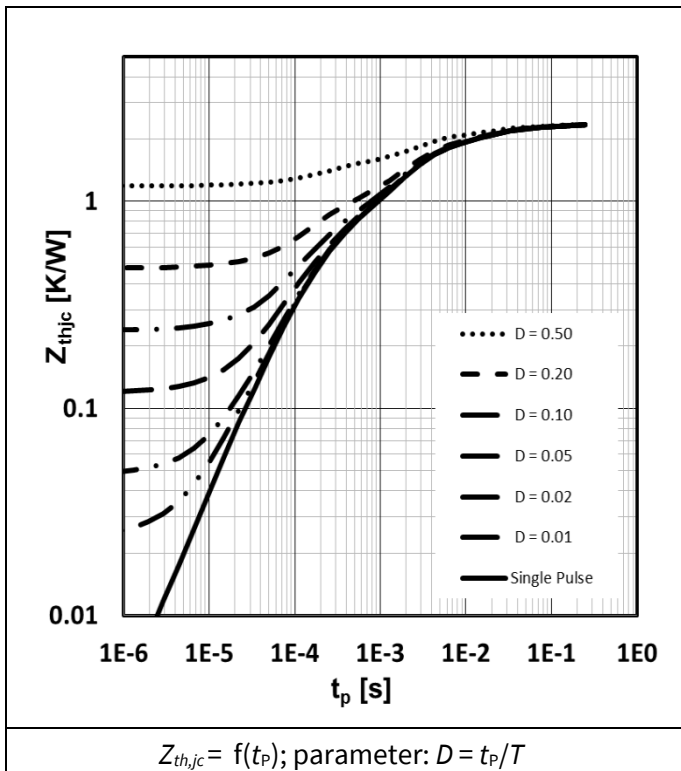


Figure 7 Max. transient thermal impedance

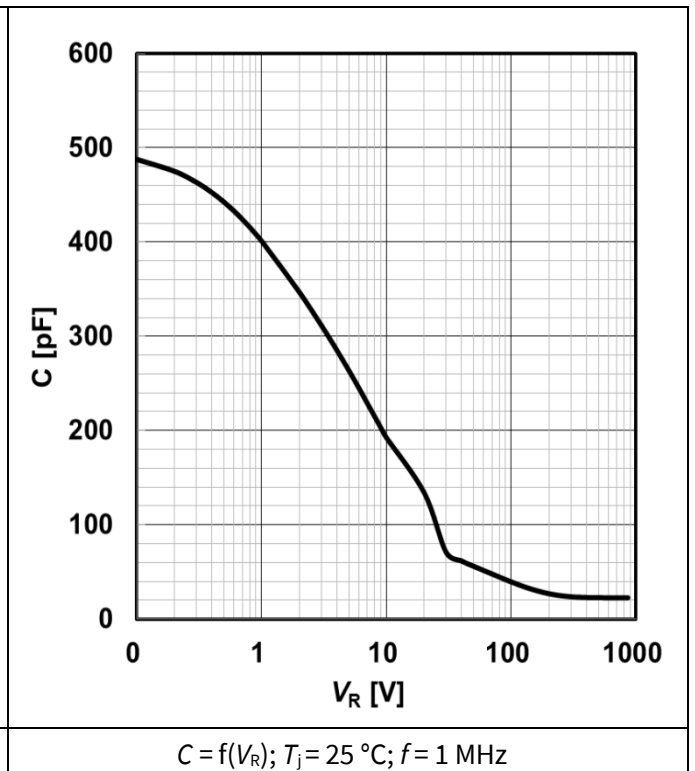


Figure 8 Typ. capacitance vs. reverse voltage

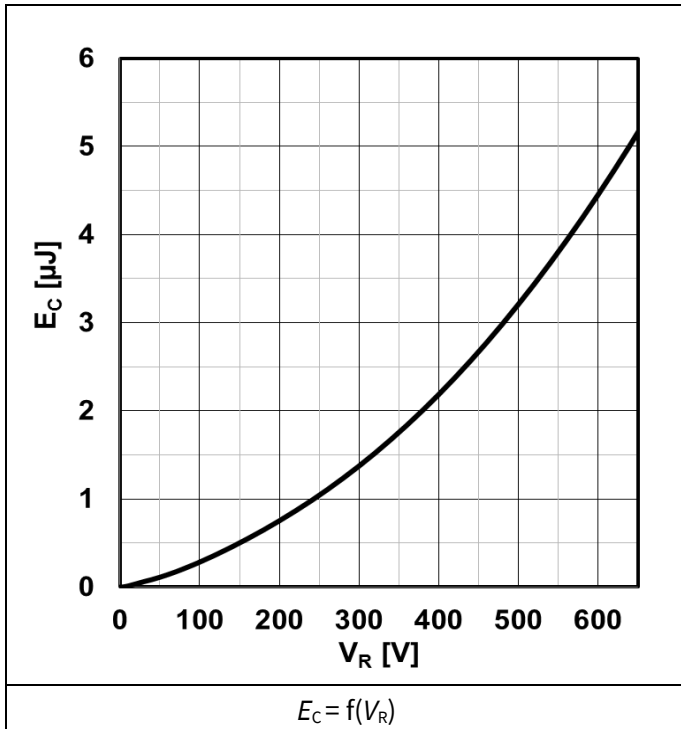


Figure 9 Typ. capacitance stored energy

5 Simplified forward characteristic

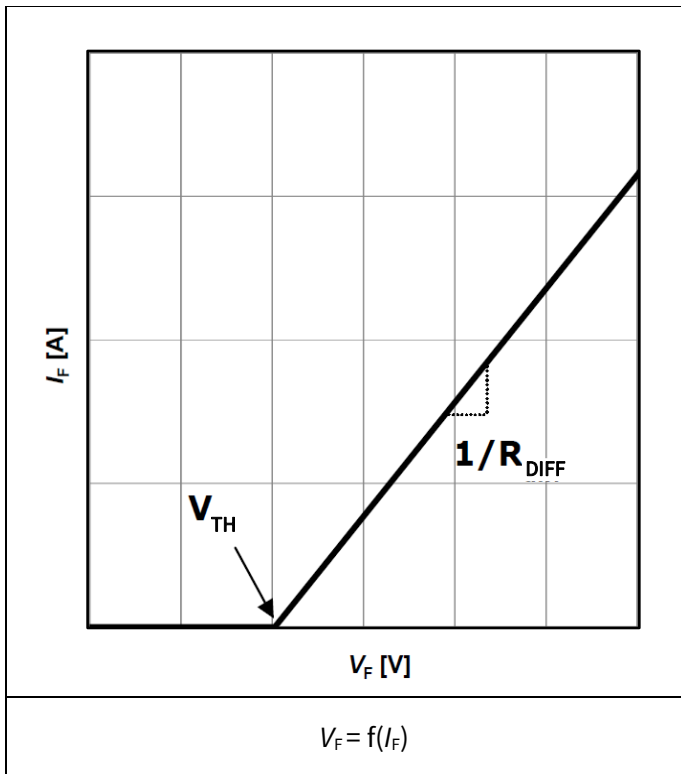


Figure 10 Equivalent forward current curve

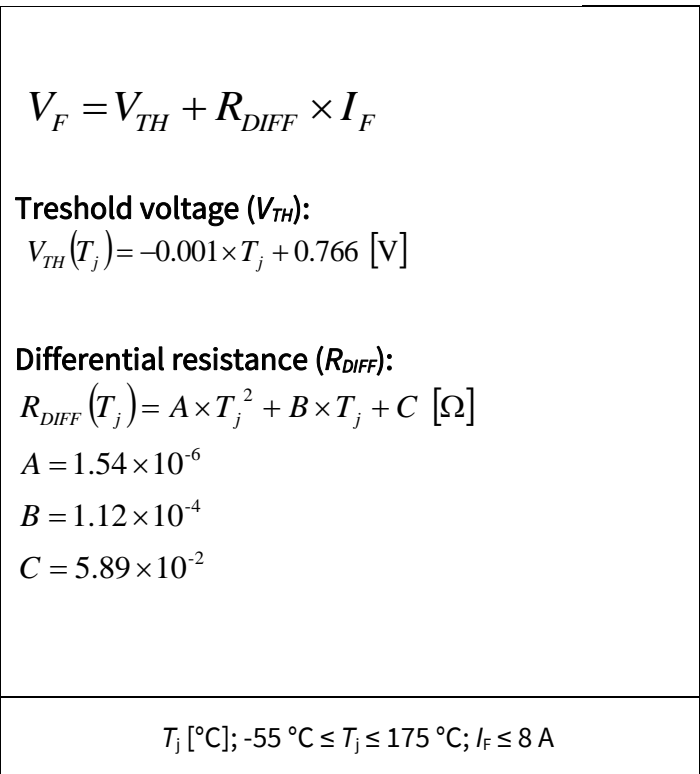


Figure 11 Mathematical Equation

6 Package outlines



Figure 12 Outlines of the package PG-TO220-2, dimensions in mm/inches

Revision History

Major changes since the last revision

Revision	Date	Subject (major changes since last revision)
2.0	2017-05-23	Release of final version

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Email: erratum@infineon.com

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